

**AMENDMENTS TO THE CLAIMS, COMPLETE LISTING OF CLAIMS**  
**IN ASCENDING ORDER WITH STATUS INDICATOR**

Please amend the following claims as indicated.

1. (Previously Presented) A method for severing a brittle material substrate by inscribing a scribe line on a brittle material substrate, while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate,

wherein the scribe line is formed with a scribe head comprising a cutter wheel with grooves formed in a blade-edge ridge thereof and a tip holder that rotatably supports the cutter wheel, and

wherein the method comprises a first scribing step of pressing and rolling the cutter wheel on a protective material by moving the tip holder in a horizontal direction, in a state in which the protective material is provided on at least one substrate surface of the brittle material substrate, thereby inscribing a scribe line on the brittle material substrate, while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate.

2. (Previously Presented) The method for severing a brittle material substrate according to claim 1, further comprising a protective material processing step of providing a protective material on at least one substrate surface of the brittle material substrate, before the scribing step.

3. (Currently Amended) The method for severing a brittle material substrate according to claim 1 or 2, wherein the brittle material substrate is a ~~single-plate~~ single-plated brittle material substrate.

4. (Previously Presented) The method for severing a brittle material substrate according to claim 3, further comprising a breaking step of breaking the brittle material substrate, after the scribing step.

5. (Previously Presented) The method for severing a brittle material substrate according to claim 4, further comprising a protective material cutting step of cutting the protective material, after the breaking step.

6. (Previously Presented) The method for severing a brittle material substrate according to claim 3, further comprising a protective material cutting step of cutting the protective material, after the scribing step.

7. (Previously Presented) The method for severing a brittle material substrate according to claim 3, further comprising a first film processing step of applying a first protective film on the protective material on the side of a first substrate surface that has been scribed, after the scribing step and before breaking the brittle material substrate.

8. (Previously Presented) The method for severing a brittle material substrate according to claim 3, further comprising a second film processing step of applying a second protective film on a second substrate surface that is different from the first substrate surface that is to be scribed, before the scribing step.

9. (Previously Presented) The method for severing a brittle material substrate according to claim 7, further comprising a breaking step of breaking the brittle material substrate, after applying the first protective film.

10. (Previously Presented) The method for severing a brittle material substrate according to claim 9, further comprising a third film processing step of peeling off the second protective film, after the breaking step.

11. (Original) The method for severing a brittle material substrate according to claim 8, further comprising a protective material cutting step of cutting the protective material and/or the protective film provided on the second substrate surface.

12. (Original) The method for severing a brittle material substrate according to claim 1 or 2, wherein the brittle material substrate is a bonded brittle material substrate formed by bonding together a first substrate and a second substrate.

13. (Previously Presented) The method for severing a brittle material substrate according to claim 12,

wherein the scribe line is formed with a scribe head comprising a cutter wheel with grooves formed in a blade-edge ridge thereof and a tip holder that rotatably supports the cutter wheel, and

wherein the method further comprises, before scribing the first substrate in the first scribing step, a second scribing step of pressing and rolling the cutter wheel on a protective material by moving the tip holder in a horizontal direction, in a state in which the protective material is provided on a surface of at least one of the first substrate and the second substrate, thereby inscribing a scribe line on the second substrate, while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate.

14. (Previously Presented) The method for severing a brittle material substrate according to claim 13, further comprising a first breaking step of breaking the second substrate, after scribing the second substrate in the first scribing step.

15. (Previously Presented) The method for severing a brittle material substrate according to claim 13, further comprising a second breaking step of breaking the first substrate, after scribing the first substrate in the first scribing step.

16. (Previously Presented) The method for severing a brittle material substrate according to claim 13, further comprising: a first film processing step of applying a first protective film on the second substrate, before scribing the second substrate in the second scribing step; and a second film

processing step of peeling off the first protective film from the second substrate, before scribing the first substrate in the first scribing step.

17. (Previously Presented) The method for severing a brittle material substrate according to claim 15, further comprising a second film processing step of applying a second protective film on the second substrate, after scribing the second substrate in the second scribing step and before breaking the scribed second substrate in the first breaking step.

18. (Original) The method for severing a brittle material substrate according to claim 15, further comprising a third film processing step of applying a third protective film on the first substrate, after scribing the first substrate in the first scribing step and before breaking the first substrate in the first breaking step.

19. (Original) The method for severing a brittle material substrate according to claim 1 or 2, wherein the brittle material substrate is a brittle material substrate provided with a functional layer.

20. (Original) The method for severing a brittle material substrate according to claim 19, further comprising a breaking step of breaking the brittle material substrate provided with the functional layer, after the scribing in the first scribing step.

21. (Original) The method for severing a brittle material substrate according to claim 20, further comprising a protective material cutting step of cutting the protective material, after breaking the brittle material substrate provided with the functional layer in the breaking step.

22. (Original) The method for severing a brittle material substrate according to claim 19, further comprising: a first film processing step of applying a first protective film on a surface of the brittle material substrate provided with the functional layer that is different from a surface on which

the functional layer is provided, before the scribing in the first scribing step; and a protective material cutting step of cutting the protective material and/or the first protective film.

23. (Original) The method for severing a brittle material substrate according to claim 22, further comprising a breaking step of breaking the brittle material substrate provided with the functional layer, after the scribing in the first scribing step.

24. (Original) The method for severing a brittle material substrate according to claim 23, further comprising: a second film processing step of applying a second protective film on that surface of the brittle material substrate provided with the functional layer on which the functional layer is provided, after the scribing in the first scribing step and before breaking the brittle material substrate provided with the functional layer in the breaking step; and a third film processing step of peeling off the second protective film, after breaking the brittle material substrate provided with the functional layer in the breaking step.

25. (Original) The method for severing a brittle material substrate according to claim 19, wherein the functional layer is a protective material also having a function to protect the brittle material substrate.

26. (Original) The method for severing a brittle material substrate according to claim 1, wherein the protective material provided on a surface of the brittle material substrate is a film.

27. (Original) The method for severing a brittle material substrate according to claim 1, wherein the protective material provided on a surface of the brittle material substrate is a coating.

28. (Previously Presented) A severing apparatus for a brittle material substrate that inscribes a scribe line on a brittle material substrate while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate,

wherein the scribe line is formed with a scribe head comprising a cutter wheel with grooves formed in a blade-edge ridge thereof and a tip holder that rotatably supports the cutter wheel, and

wherein the apparatus comprises a first scribing device that presses and rolls the cutter wheel on a protective material by moving the tip holder in a horizontal direction, in a state in which the protective material is provided on at least one substrate surface of the brittle material substrate, thereby inscribing a scribe line on the brittle material substrate, while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate.

29. (Original) The severing apparatus for a brittle material substrate according to claim 28, further comprising a protective material processing device that applies the protective material on at least one substrate surface of the brittle material substrate.

30. (Previously Presented) The severing apparatus for a brittle material substrate according to claim 28 or 29, wherein the brittle material substrate is a single-plate brittle material substrate.

31. (Original) The severing apparatus for a brittle material substrate according to claim 30, further comprising a breaking step of breaking the brittle material substrate.

32. (Original) The severing apparatus for a brittle material substrate according to claim 31, further comprising a protective material cutting device that cuts the protective material.

33. (Original) The severing apparatus for a brittle material substrate according to claim 30, further comprising a protective material cutting device that cuts the protective material.

34. (Original) The severing apparatus for a brittle material substrate according to claim 30, further comprising a first film processing device that applies a first protective film on a first substrate surface that is to be scribed.

35. (Original) The severing apparatus for a brittle material substrate according to claim 30, further comprising a second film processing device that applies a second protective film on a second substrate surface that is different from the first substrate surface.

36. (Original) The severing apparatus for a brittle material substrate according to claim 34, further comprising a breaking device that breaks the brittle material substrate.

37. (Original) The severing apparatus for a brittle material substrate according to claim 35, further comprising a third film processing device that peels off the second protective film.

38. (Original) The severing apparatus for a brittle material substrate according to claim 35, further comprising a protective material cutting device that cuts the protective material and/or the protective film provided on the second substrate surface.

39. (Original) The severing apparatus for a brittle material substrate according to claim 28 or 29, wherein the brittle material substrate is a bonded brittle material substrate formed by bonding together a first substrate and a second substrate.

40. (Previously Presented) The severing apparatus for a brittle material substrate according to claim 39,

wherein the scribe line is formed with a scribe head comprising a cutter wheel with grooves formed in a blade-edge ridge thereof and a tip holder that rotatably supports the cutter wheel, and

wherein the apparatus further comprises a second scribing device that presses and rolls the cutter wheel on a protective material by moving the tip holder in a horizontal direction, in a state in which the protective material is provided on a surface of at least one of the first substrate and the second substrate, at the same time of inscribing the scribing line on the first substrate with the first scribing device and before forming the vertical crack extending from the scribe line in a thickness

direction of the brittle material substrate, thereby inscribing a scribe line on the second substrate, while simultaneously forming a vertical crack extending from the scribe line in a thickness direction of the brittle material substrate.

41. (Previously Presented) The severing apparatus for a brittle material substrate according to claim 40, further comprising a first breaking device that breaks the second substrate.

42. (Previously Presented) The severing apparatus for a brittle material substrate according to claim 40, further comprising a second breaking device that breaks the first substrate.

43. (Original) The severing apparatus for a brittle material substrate according to claim 40, further comprising: a first film processing device that applies a first protective film on the second substrate; and a second film processing device that peels off the first protective film from the second substrate.

44. (Original) The severing apparatus for a brittle material substrate according to claim 42, further comprising a second film processing device that applies a second protective film on the second substrate.

45. (Original) The severing apparatus for a brittle material substrate according to claim 42, further comprising a third film processing device that applies a third protective film on the first substrate.

46. (Original) The severing apparatus for a brittle material substrate according to claim 28 or 29, wherein the brittle material substrate is a brittle material substrate provided with a functional layer.

47. (Original) The severing apparatus for a brittle material substrate according to claim 46, further comprising a breaking device that breaks the brittle material substrate provided with the



functional layer.

48. (Original) The severing apparatus for a brittle material substrate according to claim 47, further comprising a protective material cutting device that cuts the protective material.

49. (Original) The severing apparatus for a brittle material substrate according to claim 46, further comprising: a first film processing device that applies a first protective film on a surface of the brittle material substrate provided with the functional layer that is different from a surface on which the functional layer is provided; and a protective material cutting device that cuts the protective material and/or the first protective film.

50. (Original) The severing apparatus for a brittle material substrate according to claim 49, further comprising a breaking device that breaks the brittle material substrate provided with the functional layer.

51. (Original) The severing apparatus for a brittle material substrate according to claim 50, further comprising: a second film processing device that applies a second protective film on that surface of the brittle material substrate provided with the functional layer on which the functional layer is provided; and a third film processing device that peels off the second protective film.

52. (Original) The severing apparatus for a brittle material substrate according to claim 46, wherein the functional layer is a protective material also having a function to protect the brittle material substrate.

53. (Original) The severing apparatus for a brittle material substrate according to claim 28, wherein the protective material provided on the surface of brittle material substrate is a film.

54. (Cancelled).

55. (Previously Presented) The method for severing a brittle material substrate according to claim 1,

wherein the cutter wheel with grooves formed in the ridge thereof has protrusions, and the protrusions are brought into contact with the brittle material substrate while applying intermittent shocks to the brittle material substrate, at the time of inscribing the scribe line on the brittle material substrate by pressing and rolling on the protective material, thereby facilitating inscribing of the scribe line.

56. (Currently Amended) ~~The method for severing~~ apparatus for a brittle material substrate according to claim 28,

wherein the cutter wheel with grooves formed in the ridge thereof has protrusions, and the protrusions are brought into contact with the brittle material substrate while applying intermittent shocks to the brittle material substrate, at the time of inscribing the scribe line on the brittle material substrate by pressing and rolling on the protective material, thereby facilitating inscribing of the scribe line.